



HEX-300B

Halogen Free

HALL ELEMENT

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1.Application

This specification Sheet is applied to Hall sensor that HEX.TEC supplies.

2. Electrical Characteristics

2.1 Maximum Ratings

(Ta : 25°C)

Parameter	Symbol	Rating	Unit
Maximum Input Current	I _{max}	20 (at 25°C)	mA
Maximum Power Dissipation	P _{max}	150 (at 25°C)	mW
Operating Temperature Range	T _{op}	-40 ~ +120	°C
Storage Temperature Range	T _{st}	-40 ~ +150	°C

2.2 Electrical Characteristics (Measured at 25°C)

Parameter	Symbol	Measurement Conditions	Min	Max	Unit
Output Hall Voltage	V _H	V _{in} =1V, B=500G	168	274	mV
Input Resistance	R _{in}	I=0.1mA	240	550	Ω
Output Resistance	R _{out}	I=0.1mA	240	550	Ω
Offset Voltage	V _O	V _{in} =1V, B=0G	-7	+7	mV
Temp. Coeff. of V _H	α	T _a =0 ~ +40°C	—	-1.8	% /°C
Temp. Coeff. of R _{in} , R _{out}	β	T _a =0 ~ +40°C	—	-1.8	% /°C

※ V_H=V_{HM}-V_O (V_{HM} : The output voltage measured at 500G.)

2.3 Rank Classification and Mark on Output Hall Voltage

Output Hall Voltage, V _H (mV)	Rank	Mark	Measurement Conditions
168 ~ 204	C	▪ C	V _{in} =1V, B=500G (Constant Voltage)
196 ~ 236	D	▪ D	
228 ~ 274	E	▪ E	
266 ~ 320	F	▪ F	

3. Method for Mounting

3.1 Lead Frame

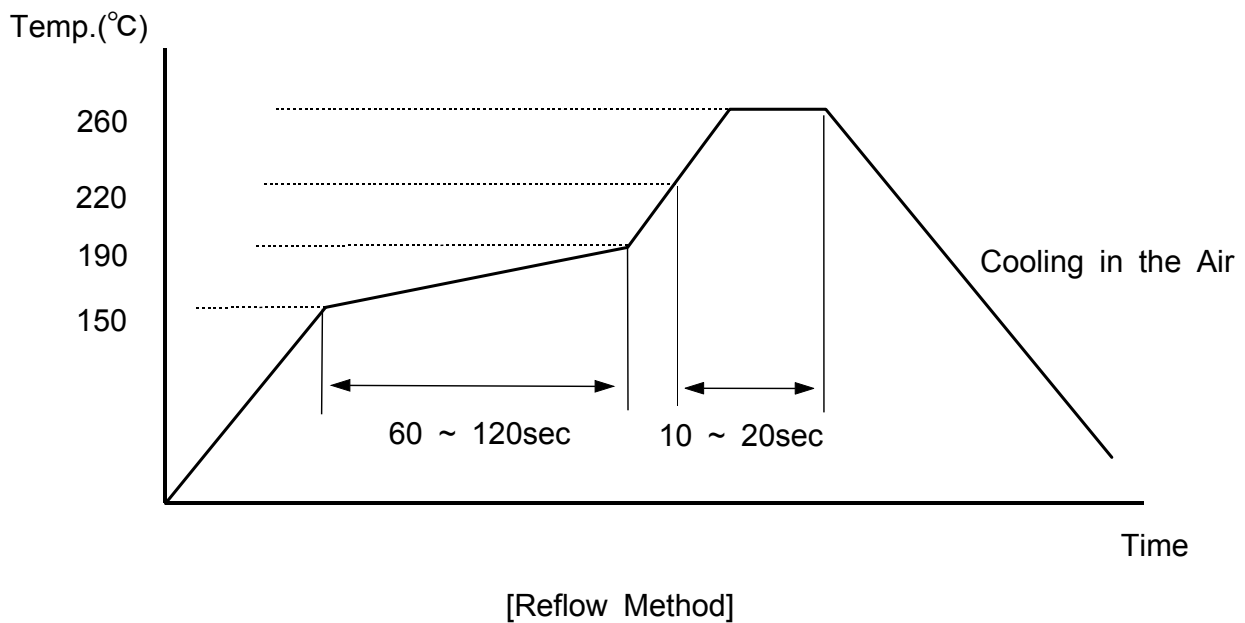
- 1) The material of lead frame is phosphor bronze alloy and the die bonded surface is plated by silver. The minimum thickness of plating is $3.0\mu\text{m}$.
- 2) Lead Frame is plated by pure Sn and the thickness is controlled by $4\sim 12\mu\text{m}$.

3.2 Soldering Conditions on PCB

- 1) No rapid heating and cooling is desired.
- 2) Preheating is recommended for $1\sim 2$ minutes at $150\sim 190^\circ\text{C}$.
- 3) Reflowing is recommended for $10\sim 20$ seconds at $220\sim 260^\circ\text{C}$.

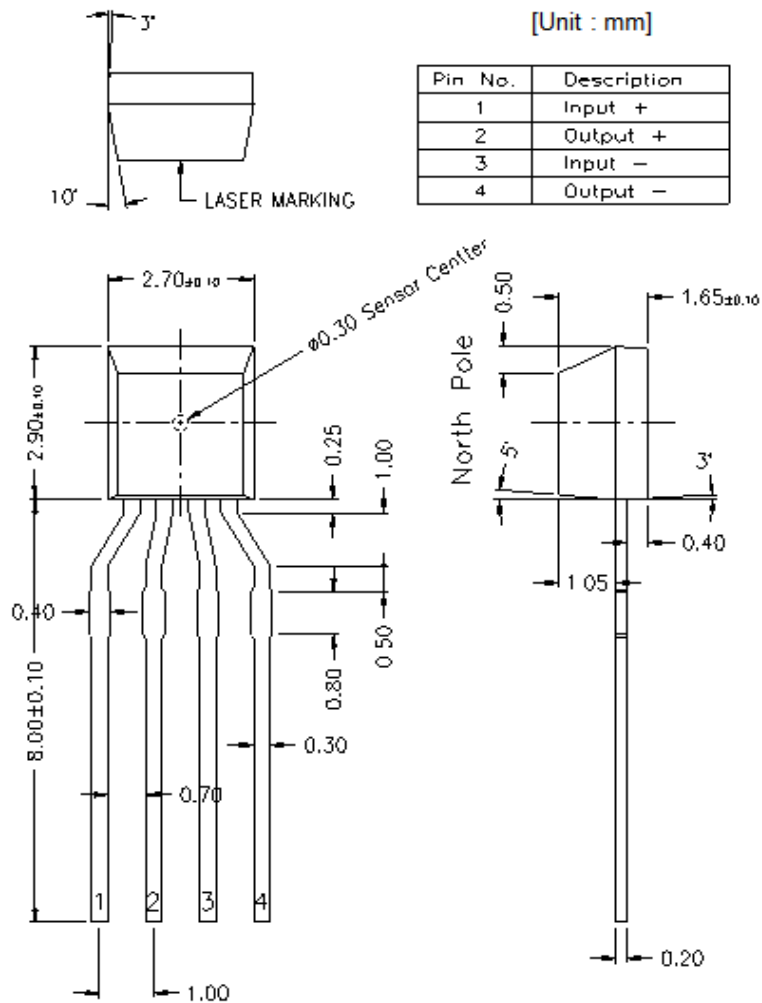
3.3 Soldering Method and Temperature

Items	Methods	Temperature
Reflow	Soldering by passing the heated zone	Max 260°C in 10sec
Solder Iron	Soldering by solder-iron	Max 350°C in 3sec



4. External Dimensions and Appearance

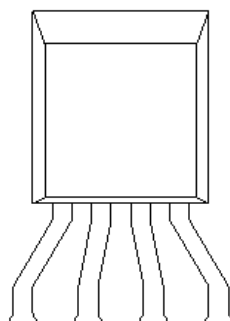
4.1 External Dimensions (Unit:mm)



[Package Dimensions]

4.2 Marking Method

Devices should be marked by LASER beam in the form of 「 Rank' 」



5. Packaging : Bulk packaging (500pcs per pack)

6. RELIABILITY

6.1 TEST Item and Condition

No	TEST Item	TEST Condition
1	HIGH TEMP. STORAGE	Ta=150°C,t=1000HR
2	HIGH TEMP. OPERATION	Ta=120°C,Iopr=10mA,t=1000HR
3	LOW TEMP. OPERATION	Ta=-40°C,Iopr=6mA,t=1000HR
4	HIGH TEMP. HIGH HUMIDITY OPERATION	Ta=85°C,HR=85%,Iopr=9mA,t=1000HR
5	PCT	Ta=121°C,HR=100%,Pv=2atm,t=24HR
6	THERMAL SHOCK	T(L)=-55°C,T(H)=150°C,t=(L,H)=30min,M=30CYCLE
7	HIGH HUMIDITY TEMPERATURE CYCLE	T(L)=-20°C,T(H)=85°C,t(L,H)=30min,HR=95%,M=40CYCLE
8	SOLDERING HEAT RESISTANCE	Peak Temp=260°C,t=10sec,REFLOW
9	ESD(MM)	V=500V,C=200pF,R=0Ω(EIAJ TEST CONDITION)

6.2 Criterion For Judging

After each reliability test, samples should be during at least 24 hrs in room temp. & humidity, and then measure. The change rates should be in the values as below.

Item	OK Spec.	NG/OK
Rin	Under Initial±20%	OK (Spec. Satisfying)
Rout		
VH		
Vo	Max. ±15mV	

7. Caution on treating

On surface mounting, please keep the statements written by mounting conditions.

Safekeeping Period is 6 month at room temperature in condition of being packed

8. The Analysis of RoHS(Restriction of Hazardous Substances)

It is guaranteed that there are no RoHS materials in Hall Sensor by specific analysis results

- References : RoHS 6 Materials

- 1) Cadmium(Cd)
- 2) Lead(Pb)
- 3) Mercury(Hg)
- 4) Hexavalent Chromium(CrVI)
- 5) PBBs(Polybrominated Biphenyls)
- 6) PBDEs(Polybrominated Diphenyl Ethers)

9. Halogen Free

HEX.TEC Hall sensor guarantees that it contains no Halogenated materials.

That is Halogen Free product and is confirmed by specific analysis results.

- References : Halogen materials

- 1) Fluorine(F)
- 2) Chlorine(Cl)
- 3) Bromine(Br)
- 4) Iodine (I)